EXHIBIT M

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December 6, 1999

Ralph R. Veseli, Patent Attorney Maria Paula Kovacs, Paralegal Intellectual Property Mail Stop D-106 LSI Logic Corporation 1551 McCarthy Blvd. Milpitas, CA 95035

Re: Patent Application Documents To Be Filed in the USPTO Sheldon Aronowitz, Valeriy Sukharev,
John Haywood, James P. Kimball, Helmut Puchner,
Ravindra Manohar Kapre, and Nicholas Eib
PROCESS FOR ETCHING A CONTROLLABLE
THICKNESS OF OXIDE ON AN INTEGRATED
CIRCUIT STRUCTURE ON A SEMICONDUCTOR
SUBSTRATE USING NITROGEN PLASMA AND
AN RF BIAS APPLIED TO THE SUBSTRATE
LSI Docket No. 99-039

Dear Ralph:

Per our telephone conversation, enclosed are the following documents which are to be submitted to the United States Patent and Trademark Office along with the patent application, formal drawings, declaration, and assignment, which were sent to your office on December 4, 1999, via Federal Express, in connection with the filing of a patent application for the above captioned LSI Logic patent docket:

- 1) Transmittal Form (to be signed by you, Ralph, and dated);
- 2) Recordation Form Cover Sheet for assignment (to be signed by you, Ralph, and also completed and dated);
- 3) Information Disclosure Statement (already signed, but to be dated) and two (2) sets of five (5) accompanying disclosures (1 set for LSI Logic and 1 set for the USPTO); and
- 4) Express Mailing Label.

Ralph R. Veseli, Patent Attorney Page Two

Also enclosed is a copy of the application (with drawing attached) as well as a floppy disk with the application and formal papers in WordPerfect 5.2 for Windows format. We are not, however, sending you postcards since you have your own preferred format for same.

A copy of the application will also be sent to each of the inventors at a later date.

My statement for services with copies of expenses attached will be sent under separate cover.

Regards,

John P. Taylor

John P. Jaylor

Patent Attorney